



Material Content Data Sheet



Sales Product Name	BBY 58-06W H6327			Issued		29. August 2013		
MA#	MA000857392							
Package	PG-SOT323-3-1			Weight*		5.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		10	
	noble metal	gold	7440-57-5	0.006	0.10		1003	
	inorganic material	silicon	7440-21-3	0.051	0.86	0.96	8570	9583
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		440	
	non noble metal	chromium	7440-47-3	0.008	0.13		1321	
	non noble metal	copper	7440-50-8	2.617	43.85	44.03	438480	440329
wire	non noble metal	copper	7440-50-8	0.012	0.21	0.21	2093	2093
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5241	
	plastics	epoxy resin	-	0.672	11.27		112678	
	inorganic material	silicondioxide	60676-86-0	2.424	40.62	52.41	406164	524083
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22234	22234
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1678	1678
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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